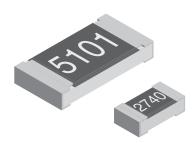
Vishay



High Stability Thin Film Flat Chip Resistors



TNPW e3 precision thin film flat chip resistors are the perfect choice for most fields of modern electronics where highest reliability and stability is of major concern. Typical applications include test and measuring equipment, medical equipment, industrial, and automotive.

FEATURES

- · Low temperature coefficient and tight tolerances (± 0.1 %; ± 10 ppm/K)
- Superior moisture resistivity ≤ 0.25 % (85 °C; 56 days; 85 % RH)
- · Excellent overall stability at different environmental conditions ≤ 0.05 % (1000 h rated power at 70 °C)
- AEC-Q200 qualified (sizes 0402 to 1206)
- · Waste gas resistant
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

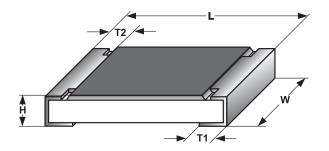
- · Test and measuring equipment
- · Medical equipment
- · Industrial equipment
- Automotive

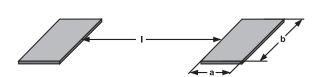
| STANDARD EL | ECTRICAL | SPECIFICA | TIONS | | | | | |
|---|-------------------------------|-------------------------------|-----------------------------|-----------------------------|--------------------------------|--------------------------------|--------------------------------|--|
| DESCRIPTION | TNPW0402 e3 | TNPW0603 e3 | TNPW0805 e3 | TNPW1206 e3 | TNPW1210 e3 (1) | TNPW2010 e3 | TNPW2512 e3 (1) | |
| Metric size | RR 1005M | RR 1608M | RR 2012M | RR 3216M | RR 3225M | RR 5025M | RR 6332M | |
| Resistance range | 10 Ω to 100 k Ω | 10 Ω to 332 k Ω | 10 Ω to 1 M Ω | 10 Ω to 2 M Ω | 10 Ω to 3.01 M Ω | 10 Ω to 4.99 M Ω | 10 Ω to 8.87 M Ω | |
| Resistance tolerance | | | = | ± 1 %; ± 0.5 %; | ± 0.1 % | | | |
| Temperature coefficent | | ± 50 ppm/K; ± 2 | 5 ppm/K; ± 15 p | pm/K; ± 10 ppm | /K | ± 50 ppm/K | ; ± 25 ppm/K | |
| Rated dissipation, $P_{70}^{(2)}$ | 0.063 W | 0.1 W | 0.125 W | 0.25 W | 0.33 W | 0.4 W | 0.5 W | |
| Operating voltage, U _{max.} AC/DC | 50 V | 75 V | 150 V | 200 V | 200 V | 300 V | 300 V | |
| Permissible film temperature, $g_{\rm F}$ max. | | 155 °C | | | | | | |
| Operating temperature range | | | - : | 55 °C to 125 °C | (155 °C) | | | |
| Thermal resistance (3) | 870 K/W | 550 K/W | 440 K/W | 220 K/W | 170 K/W | 140 K/W | 110 K/W | |
| Max. resistance change at P_{70} ; $\Delta R/R$: | 10 Ω to 100 k Ω | 10 Ω to 332 k Ω | 10 Ω to 1 M Ω | 10 Ω to 2 M Ω | 10 Ω to 3.01 M Ω | 10 Ω to 4.99 M Ω | 10 Ω to 8.87 M Ω | |
| 1000 h | ≤ 0.05 % | ≤ 0.05 % | ≤ 0.05 % | ≤ 0.05 % | ≤ 0.05 % | ≤ 0.05 % | ≤ 0.05 % | |
| 8000 h | ≤ 0.10 % | ≤ 0.10 % | ≤ 0.10 % | ≤ 0.10 % | ≤ 0.10 % | ≤ 0.10 % | ≤ 0.10 % | |
| 225 000 h | ≤ 0.30 % | ≤ 0.30 % | ≤ 0.30 % | ≤ 0.30 % | ≤ 0.30 % | ≤ 0.30 % | ≤ 0.30 % | |
| Insulation voltage: | | | | | | | | |
| U _{ins} 1 min | 75 V | 100 V | 200 V | 300 V | 300 V | 300 V | 300 V | |
| Continuous | 75 V | 75 V | 75 V | 75 V | 75 V | 75 V | 75 V | |
| Failure rate: FIT _{observed} | ≤ 0.1 x 10 ⁻⁹ /h | ≤ 0.1 x 10 ⁻⁹ /h | ≤ 0.1 x 10 ⁻⁹ /h | ≤ 0.1 x 10 ⁻⁹ /h | ≤ 0.1 x 10 ⁻⁹ /h | ≤ 0.1 x 10 ⁻⁹ /h | ≤ 0.1 x 10 ⁻⁹ /h | |

- TNPW 0402 without marking.
- (1) Size not specified in EN 140401-801.
- (2) Rated voltage $\sqrt{P \times R}$. The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). Using advanced temperature level may require special considerations towards the choice of circuit board and solder material. The rated dissipation applies only if the permitted film temperature is not exceeded.
- (3) Measuring conditions in accordance with EN 140401-801.



DIMENSIONS





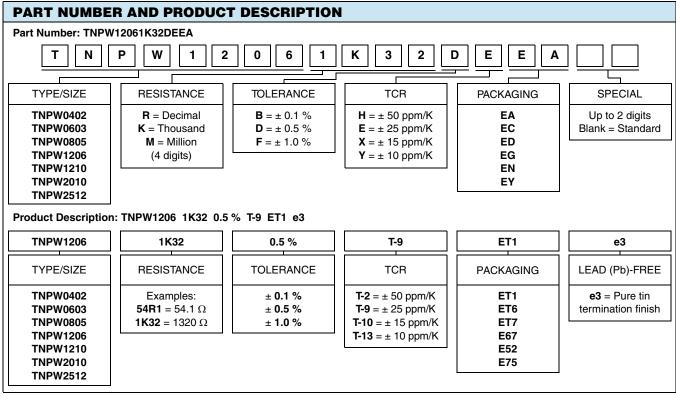
| DIMENSIONS AND MASS | | | | | | | | |
|---------------------|----------------|-----------------|-----------------|----------------|--------------|--|--|--|
| TYPE | L (mm) | W (mm) | H (mm) | T1/T2 (mm) | MASS (mg) | | | |
| TNPW0402 e3 | 1.0 ± 0.05 | 0.5 ± 0.05 | 0.35 ± 0.05 | 0.2 ± 0.10 | 0.65 | | | |
| TNPW0603 e3 | 1.6 ± 0.10 | 0.85 ± 0.10 | 0.45 ± 0.10 | 0.3 ± 0.20 | 2 | | | |
| TNPW0805 e3 | 2.0 ± 0.15 | 1.25 ± 0.15 | 0.45 ± 0.10 | 0.4 ± 0.20 | 5.5 | | | |
| TNPW1206 e3 | 3.2 ± 0.15 | 1.6 ± 0.15 | 0.55 ± 0.10 | 0.5 ± 0.25 | 10 | | | |
| TNPW1210 e3 | 3.2 ± 0.15 | 2.45 ± 0.15 | 0.60 ± 0.15 | 0.5 ± 0.25 | 16 | | | |
| TNPW2010 e3 | 5.0 ± 0.15 | 2.5 ± 0.15 | 0.60 ± 0.15 | 0.6 ± 0.25 | 28 | | | |
| TNPW2512 e3 | 6.3 ± 0.20 | 3.1 ± 0.15 | 0.60 ± 0.15 | 0.6 ± 0.25 | 39 | | | |

| SOLDER PAD DIMENSIONS | | | | | | | |
|-----------------------|------------------|-----------|-----------|----------------|-----------|-----------|--|
| | REFLOW SOLDERING | | | WAVE SOLDERING | | | |
| TYPE | a (mm) | b (mm) | l (mm) | a (mm) | b (mm) | l (mm) | |
| TNPW0402 e3 | 0.4 | 0.6 | 0.5 | - | - | - | |
| TNPW0603 e3 | 0.5 | 0.9 | 1.0 | 0.9 | 0.9 | 1.0 | |
| TNPW0805 e3 | 0.7 | 1.3 | 1.2 | 0.9 | 1.3 | 1.3 | |
| TNPW1206 e3 | 0.9 | 1.7 | 2.0 | 1.1 | 1.7 | 2.3 | |
| TNPW1210 e3 | 0.9 | 2.5 | 2.0 | 1.1 | 2.5 | 2.3 | |
| TNPW2010 e3 | 1.0 | 2.5 | 3.9 | 1.2 | 2.5 | 3.9 | |
| TNPW2512 e3 | 1.0 | 3.2 | 5.2 | 1.2 | 3.2 | 5.2 | |

| TYPE | TCR | TOLERANCE | RESISTANCE | E-SERIES | |
|----------------|------------|-----------|---------------|----------|--|
| | | ± 1 % | 10R to 100K | 24; 96 | |
| | ± 50 ppm/K | ± 0.5 % | 10R to 100K | 24; 192 | |
| | T | ± 0.1 % | 47R to 100K | | |
| TNDW0400 -0 | | ± 1 % | 10R to 100K | 24; 96 | |
| TNPW0402 e3 | ± 25 ppm/K | ± 0.5 % | 10R to 100K | | |
| | | ± 0.1 % | | 04: 100 | |
| | ± 15 ppm/K | ± 0.1 % | 47R to 100K | 24; 192 | |
| | ± 10 ppm/K | ± 0.1 % | | | |
| | | ± 1 % | 10R to 332K | 24; 96 | |
| | ± 50 ppm/K | ± 0.5 % | 10R to 332K | 24; 192 | |
| TNPW0603 e3 | | ± 0.1 % | 10h to 332k | | |
| | | ± 1 % | 10R to 332K | 24; 96 | |
| | ± 25 ppm/K | ± 0.5 % | 10R to 332K | 24; 192 | |
| | | ± 0.1 % | 10H to 332K | | |
| | ± 15 ppm/K | ± 0.1 % | 47R to 332K | | |
| | ± 10 ppm/K | ± 0.1 % | | | |
| | | ± 1 % | 10R to 1M0 | 24; 96 | |
| | ± 50 ppm/K | ± 0.5 % | 10R to 1M0 | 24; 192 | |
| | | ± 0.1 % | | | |
| TNPW0805 e3 | | ± 1 % | 10R to 1M0 | 24; 96 | |
| 1141 440003 63 | ± 25 ppm/K | ± 0.5 % | 10R to 1M0 | | |
| | | ± 0.1 % | TOTA TO TIMO | 24; 192 | |
| | ± 15 ppm/K | ± 0.1 % | 47R to 1M0 | 24, 102 | |
| | ± 10 ppm/K | ± 0.1 % | | | |
| | | ± 1 % | 10R to 2M0 | 24; 96 | |
| | ± 50 ppm/K | ± 0.5 % | 10R to 2M0 | 24; 192 | |
| | | ± 0.1 % | | , | |
| TNPW1206 e3 | | ± 1 % | 10R to 2M0 | 24; 96 | |
| | ± 25 ppm/K | ± 0.5 % | 10R to 2M0 | | |
| | | ± 0.1 % | 1011 to 21110 | 24; 192 | |
| | ± 15 ppm/K | ± 0.1 % | 47R to 2M0 | 27, 102 | |
| | ± 10 ppm/K | ± 0.1 % | 4711 to 21010 | | |



| TYPE | TCR | TOLERANCE | RESISTANCE | E-SERIES | |
|-------------|------------|-----------|-------------|----------|--|
| | | ± 1 % | 10R to 3M01 | 24; 96 | |
| | ± 50 ppm/K | ± 0.5 % | 10R to 3M01 | 24; 192 | |
| | | ± 0.1 % | 47R to 2M13 | 24, 192 | |
| TNPW1210 e3 | | ± 1 % | 10R to 3M01 | 24; 96 | |
| 1NPW1210 e3 | ± 25 ppm/K | ± 0.5 % | 10R to 3M01 | | |
| | | ± 0.1 % | | 24; 192 | |
| | ± 15 ppm/K | ± 0.1 % | 47R to 2M13 | | |
| | ± 10 ppm/K | ± 0.1 % | | | |
| | | ± 1 % | 10R to 4M99 | 24; 96 | |
| | ± 50 ppm/K | ± 0.5 % | 10R to 4M99 | 24: 102 | |
| TNPW2010 e3 | | ± 0.1 % | 47R to 1M0 | 24; 192 | |
| TNPW2010 e3 | | ± 1 % | 10R to 4M99 | 24; 96 | |
| | ± 25 ppm/K | ± 0.5 % | 10R to 4M99 | 04: 100 | |
| | | ± 0.1 % | 47R to 1M0 | 24; 192 | |
| | | ± 1 % | 10R to 8M87 | 24; 96 | |
| | ± 50 ppm/K | ± 0.5 % | 10R to 8M87 | 04: 100 | |
| TNDW0510 60 | | ± 0.1 % | 47R to 1M0 | 24; 192 | |
| TNPW2512 e3 | | ± 1 % | 10R to 8M87 | 24; 96 | |
| | ± 25 ppm/K | ± 0.5 % | 10R to 8M87 | | |
| | | ± 0.1 % | 47R to 1M0 | 24; 192 | |



Note

• The product can be ordered using either the PART NUMBER or the PRODUCT DESCRIPTION.

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| PACKAGING | | | | | | | | |
|--|--------------|----------|--------------------------------|----------|-------|---------------|--|--|
| TYPE | CODE | QUANTITY | CARRIER TAPE | WIDTH | PITCH | REEL DIAMETER | | |
| TNPW0402 e3 | ET7 = ED | 10 000 | | 8 mm | 2 mm | 180 mm / 7" | | |
| TNPW0603 e3 TNPW0805 e3 TNPW1206 e3 TNPW1210 e3 | E52 = EN | 1000 (1) | Paper tape acc. IEC 60286-3 | | 4 mm | 180 mm / 7" | | |
| | ET1 = EA 500 | 5000 | Type I | O IIIIII | | | | |
| | ET6 = EC | 20 000 | | | 4 mm | 330 mm / 13" | | |
| TNPW2010 e3 | E75 = EY | 1000 | Blister tape | | | | | |
| TNPW2512 e3 | E75 = EY | 1000 | acc. IEC 60286-3 | 12 mm | 4 mm | 180 mm / 7" | | |
| | E67 = EG | 2000 | туре п | | | | | |

Note

DESCRIPTION

Production is strictly controlled and follows an extensive set of instructions established for reproducibility. A homogeneous film of metal alloy is deposited on a high grade Al₂O₃ ceramic substrate and conditioned to achieve the desired temperature coefficient. Specially designed inner contacts are deposited on both sides. A special laser is used to achieve the target value by smoothly fine trimming the resistive layer without damaging the ceramics. A further conditioning is applied in order to stabilize the trimming result. The resistor elements are covered by a protective coating designed for electrical, mechanical and climatic protection. The terminations receive a final pure tin on nickel plating. The result of the determined production is verified by an extensive testing procedure on 100 % of the individual chip resistors. This includes pulse load screening for the elimination of products with a potential risk of early life failures according to EN 140401-801, 2.1.2.2. Only accepted products are laid directly into the tape in accordance with EN 60286-3.

ASSEMBLY

The resistors are suitable for processing on automatic SMD assembly systems. They are suitable for automatic soldering using wave, reflow or vapour phase as shown in IEC 61760-1. The encapsulation is resistant to all cleaning solvents commonly used in the electronics industry, including alcohols, esters and aqueous solutions. The suitability of conformal coatings, if applied, shall be qualified by appropriate means to ensure the long-term stability of the whole system. The resistors are RoHS compliant, the pure tin plating provides compatibility with lead (Pb)-free and lead-containing soldering processes. The immunity of the plating against tin whisker growth has been proven under extensive testing.

All products comply with the $GADSL^{(2)}$ and the $CEFIC-EECA-EICTA^{(3)}$ list of legal restrictions on hazardous substances. This includes full compliance with the following directives:

- 2000/53/EC End of Vehicle life Directive (ELV) and Annex II (ELV II)
- 2002/95/EC Restriction of the use of Hazardous Substances Directive (RoHS)
- 2002/96/EC Waste Electrical and Electronic Equipment Directive (WEEE)

Solderability is specified for 2 years after production or re-qualification. The permitted storage time is 20 years.

RELATED PRODUCTS

The TNPW with SnPb termination plating is designed for those applications, where lead bearing terminations are mandatory. For ordering TNPW with SnPb terminations please refer to latest edition of data sheet TNPW, document number 31006.

TNPS ESCC high-reliability thin film chip resistors are the premium choice for design and manufacture of equipment, where matured technology and proven reliability are of utmost importance. They are regularly used in communication and research satellites and fit equally well into aircraft and military electronic systems. Approval of the TNPS ESCC products is granted by the European Space Components Coordination and registered in the ESCC Qualified Parts List, REP005, document number 28789.

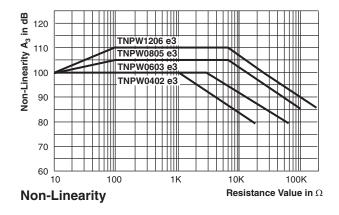
(2) Global Automotive Declarable Substance List, see www.gadsl.org.

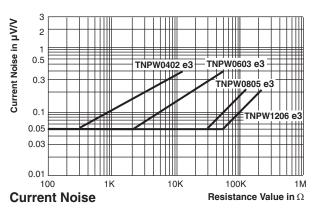
^{(1) 1000} pieces packaging is available only for precision resistors with tolerance ± 0.1 % and temperature coefficient ≤ ± 25 ppm/K.

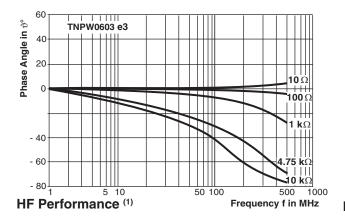
⁽³⁾ CEFIC (European Chemical Industry Council), EECA (European Electronic Component Manufacturers Association), EICTA (European trade organisation representing the information and communications technology and consumer electronics), see $\underline{\text{www.eicta.org}} \rightarrow \text{issue} \rightarrow$ environment policy \rightarrow chemicals \rightarrow chemicals for electronics.

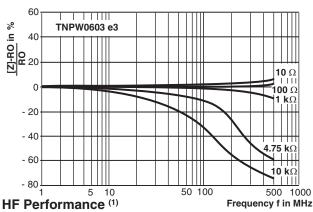


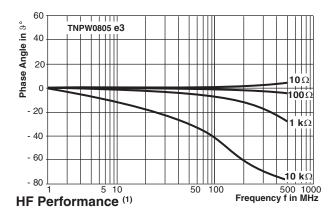
FUNCTIONAL PERFORMANCE

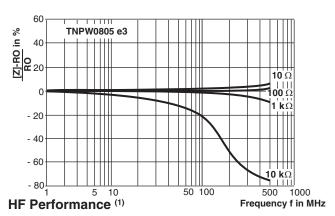










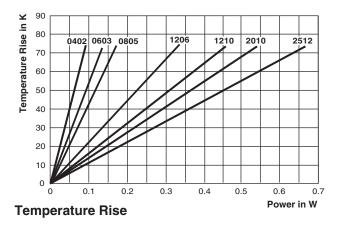


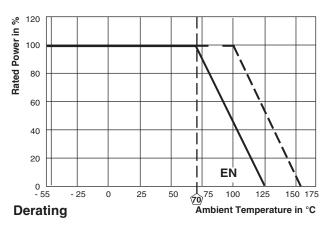
Note

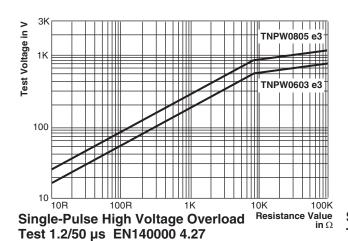
(1) Typical figures. HF-characteristic also depends on termination and circuit design.

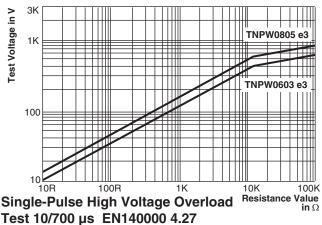


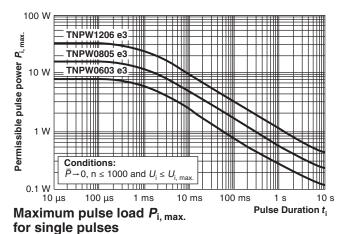


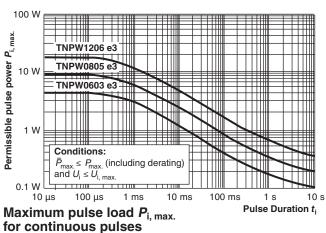




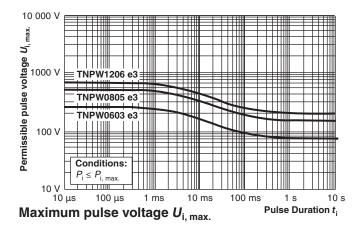












TEST AND REQUIREMENTS

All tests are carried out in accordance with the following specifications:

IEC 60115-1, generic specification (includes tests)

EN 140400, sectional specification (includes schedule for qualification approval)

EN 140401-801, detail specification (includes schedule for conformance inspection)

The testing also covers most of the requirements specified by EIA/IS-703 and JIS-C-5202. The tests are carried out under standard atmospheric conditions in accordance with IEC 60068-1, 5.3. Climatic category LCT/UCT/56 (rated temperature range: Lower category temperature, upper category temperature; damp heat, long term, 56 days) is valid. Unless otherwise specified the following values apply:

Temperature: 15 °C to 35 °C Relative humidity: 45 % to 75 %

Air pressure: 86 kPa to 106 kPa (860 mbar to 1060 mbar).

The components are mounted for testing on boards in accordance with EN 60115-1, 4.31 unless otherwise specified. The parameters stated in the Test Procedures and Requirements table are based on the required tests and permitted limits of EN 140401-801.

| TEST PR | OCEDURES | AND REQUI | REMENTS | |
|----------------------|----------------------------|---|---|--|
| EN 60115-1 CLAUSE | IEC 60068-2 TEST METHOD | TEST | PROCEDURE | REQUIREMENTS PERMISSIBLE CHANGE |
| | | | Stability for product types: | |
| | | | TNPW0402 e3 | |
| | | | TNPW0603 e3 | |
| | | | TNPW0805 e3 | |
| | | | TNPW1206 e3 | |
| | | | TNPW1210 e3 | |
| | | | TNPW2010 e3 | |
| | | | TNPW2512 e3 | |
| 4.5 | - | Resistance | | ± 1 %; ± 0.5 %; ± 0.1 % |
| 4.8.4.2 | - | Temperature coefficient | At (20/- 55/20) °C and (20/125/20) °C | ± 50 ppm/K; ± 25 ppm/K; ± 15 ppm/K; ± 10 ppm/K |
| | | Endurance at | $U = \sqrt{P_{70} \times R}$ or $U = U_{\text{max.}}$; whichever is the less severe; | |
| 4.25.1 | 4.25.1 - | 70 °C | 1.5 h on; 0.5 h off; | |
| | | | 70 °C; 1000 h | \pm (0.05 % R + 0.01 Ω) |
| | | | 70 °C; 8000 h | $\pm (0.1 \% R + 0.02 \Omega)$ |
| 4.25.3 | - | Endurance at upper category temperature | 125 °C; 1000 h 155 °C; 1000 h | ± (0.05 % R + 0.01 Ω) ± (0.1 % R + 0.02 Ω) |

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| TEST PR | TEST PROCEDURES AND REQUIREMENTS | | | | | | | |
|----------------------|----------------------------------|--|---|---|--|--|--|--|
| EN 60115-1 CLAUSE | IEC 60068-2 TEST METHOD | TEST | PROCEDURE | REQUIREMENTS PERMISSIBLE CHANGE | | | | |
| | | | Stability for product types: | | | | | |
| | | | TNPW0402 e3 | | | | | |
| | | | TNPW0603 e3 | | | | | |
| | | | TNPW0805 e3 | | | | | |
| | | | TNPW1206 e3 | | | | | |
| | | | TNPW1210 e3 | | | | | |
| | | | TNPW2010 e3 | | | | | |
| | | | TNPW2512 e3 | | | | | |
| 4.24 | 78 (Cab) | Damp heat, steady state | (40 ± 2) °C; 56 days; (93 ± 3) % RH | ± (0.1 % R + 0.01 Ω) | | | | |
| 4.23 | | Climatic sequence: | | | | | | |
| 4.23.2 | 2 (Bb) | Dry heat | UCT; 16 h | | | | | |
| 4.23.3 | 30 (Db) | Damp | 55 °C; 24 h; > 90 % RH; 1 cycle | | | | | |
| 4.23.4 | 1 (Ab) | Cold | LCT; 2 h | ± (0.1 % R + 0.02 Ω) | | | | |
| 4.23.5 | 13 (M) | Low air | 8.5 kPa; 2 h; 25 ± 10 °C | 1 (0.1 /0 // + 0.02 52) | | | | |
| 4.23.6 | 30 (Db) | Damp heat, cyclic | 55 °C; 5 days; > 95 to 100 % RH; 5 cycles | | | | | |
| 4.23.7 | - | DC load | $U = \sqrt{P_{70} \times R} \le U_{\text{max}}; 1 \text{ min}$ $LCT = -55 \text{ °C}$ $UCT = 125 \text{ °C}$ | | | | | |
| - | 1 (Ab) | Cold | - 55 °C; 2 h | ± (0.05 % R + 0.01 Ω) | | | | |
| 4.19 | 14 (Na) | Rapid change of temperature | 30 min at LCT and 30 min at UCT; LCT = -55 °C; UCT = 125 °C; 1000 cycles | ± (0.1 % R + 0.01 Ω) | | | | |
| 4.13 | - | Short time overload | $U = 2.5 \times \sqrt{P_{70} \times R}$ or $U = 2 \times U_{\text{max}}$; whichever is the less severe; 5 s | ± (0.05 % R + 0.01 Ω) | | | | |
| 4.27 | - | Single pulse high voltage overload | Severity no. 4: $U = 10 \times \sqrt{P_{70} \times R}$ or $U = 2 \times U_{\text{max}}$; whichever is the less severe; 10 pulses 10 μ s/700 μ s | \pm (0.5 % R + 0.05 Ω) no visible damage | | | | |
| 4.37 | - | Periodic electric overload | $U = \sqrt{15 \times P_{70} \times R} \text{ or }$ $U = 2 \times U_{\text{max}};$ whichever is the less severe; $0.1 \text{ s on; } 2.5 \text{ s off;}$ 1000 cycles | \pm (0.5 % R + 0.05 Ω) no visible damage | | | | |
| 4.22 | 6 (Fc) | Vibration | Endurance by sweeping; 10 Hz to 2000 Hz; no resonance; amplitude ≤ 1.5 mm or ≤ 200 m/s²; 7.5 h | \pm (0.05 % R + 0.01 Ω) no visible damage | | | | |

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High Stability Thin Film Flat Chip Resistors



| TEST PR | OCEDURES | AND REQUI | REMENTS | |
|----------------------|----------------------------|------------------------------|---|--|
| EN 60115-1 CLAUSE | IEC 60068-2 TEST METHOD | TEST | PROCEDURE | REQUIREMENTS PERMISSIBLE CHANGE |
| | | | Stability for product types: | |
| | | | TNPW0402 e3 | |
| | | | TNPW0603 e3 | |
| | | | TNPW0805 e3 | |
| | | | TNPW1206 e3 | |
| | | | TNPW1210 e3 | |
| | | | TNPW2010 e3 | |
| | | | TNPW2512 e3 | |
| | | | Solder bath method; SnPb40; non-activated flux (215 ± 3) °C; (3 ± 0.3) s | Good tinning (≥ 95 % covered); |
| 4.17.2 58 (Td) | Solderability | Solderability | Solderability Solder bath method; SnAg3Cu0.5 or SnAg3.5; non-activated flux (235 ± 3) °C; (2 ± 0.2) s | no visible damage |
| 4.18.2 | 58 (Td) | Resistance to soldering heat | Solder bath method; (260 ± 5) °C; (10 ± 1) s | ± (0.02 % R + 0.01 Ω) |
| 4.29 | 45 (XA) | Component solvent resistance | Isopropyl alcohol + 50 °C; method 2 | No visible damage |
| 4.32 | 21 (Ue ₃) | Shear | RR 1005M and RR 1608M; 9 N | No visible damage |
| 4.02 | 21 (063) | (adhesion) | RR 2012M and RR 3216M: 45 N | No visible damage |
| 4.33 | 21 (Ue ₁) | Substrate bending | Depth 2 mm, 3 times | \pm (0.05 % R + 0.01 $\Omega)$ no visible damage, no open circuit in bent position |
| 4.7 | - | Voltage proof | $U_{RMS} = U_{ins}$; 60 ± 5 s | No flashover or breakdown |
| 4.35 | - | Flammability | IEC 60695-11-5, needle flame test; 10 s | No burning after 30 s |
| - | - | Damp heat | (85 ± 5) °C; 56 days (85 ± 5) % RH | ± (0.25 R + 0.05 Ω) |

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Vishay

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